

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10776714			
<b>Filing Date:</b>	10-Feb-2004			
<b>Title of Invention:</b>	PAD STRUCTURE FOR BONDING PAD AND PROBE PAD AND MANUFACTURING METHOD THEREOF			
<b>First Named Inventor/Applicant Name:</b>	Shu-Liang Nin			
<b>Filer:</b>	Tong Wu/Sarah Dannecker			
<b>Attorney Docket Number:</b>	13732.10USD1			
Filed as Large Entity				
<b>Utility      Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
Publ. Fee- early, voluntary, or normal	1504	1	300	300
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
Utility Appl issue fee	1501	1	1400	1400

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Extension-of-Time:</b>				
<b>Miscellaneous:</b>				
Printed copy of patent - no color	8001	2	3	6
<b>Total in USD (\$)</b>				<b>1706</b>